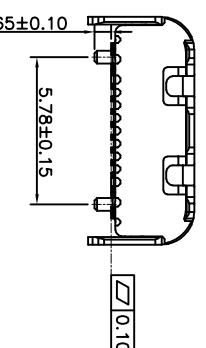
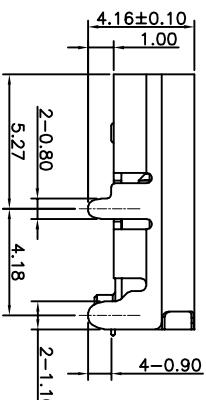
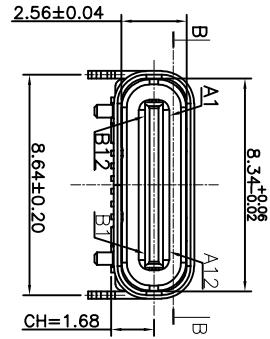
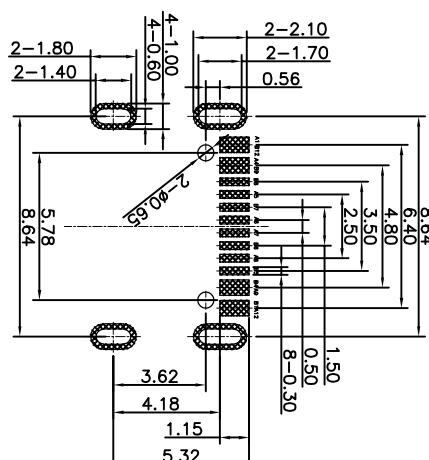
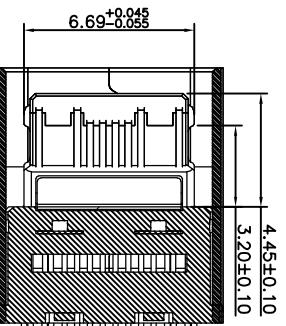
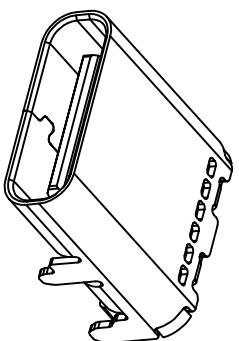
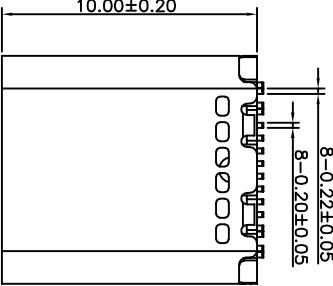


REV.	ECN NO.	DESCRIPTION	DATE	DESIGN

RECOMMENDED P.C.B LAYOUT
TOLERANCE UNSPECIFIED $\pm 0.05\text{mm}$



SPECIFICATION:
1. ELECTRICAL:
1.1 CURRENT RATING:5A;
1.2 CONTACT RESISTANCE:40mΩ Max;
1.3 DIELECTRIC WITHSTANDING VOLTAGE:1000V AC;
1.4 INSULATION RESISTANCE:100 MQ MIN;
2. MECHANICAL:
2.1 MATING FORCE:5~20N;
2.2 UNMATING FORCE:8~20N;
2.3 DURABILITY:10000 CYCLES;6~20N AFTER DURABILITY TEST;
3. MATERIAL:
3.1 HOUSING: LCP UL94V-0 BLACK;
3.2 TERMINAL:CG70225 T=0.15mm;
3.3 SHELL:SUS304 T=0.30mm;
3.4 MID PLATE:SUS304 T=0.15mm;

4. PLATING SPECIFICATION:

4.1 TERMINAL:CONTACT AREA GOLD PLATED 3u "MIN
PIN WELDING AREA GOLD FLASH.

4.2 SHELL:PLATED NI 50u" MIN

4.3 MID PLATE:CLEAR ONLY

5. ELECTROPLATED PRODUCTS NEED TO UNDERGO TIN
ADHESION TESTING. THE TIN ADHESION AREA SHOULD
REACH OVER 95%.

6. SMT REFLow Soldering (PEAK VALUE 260 °C ± 5 °C)
SHALL BE FREE OF BLISTERING, GLUE MELTING AND
POOR COLOR CHANGE (DEFORMATION WITHIN TOLERANCE)

7. OPERATING TEMPERATURE: -40°C~+85°C

PIN ASSIGNMENT:

Pin No.	Signal Name	Pin No.	Signal Name
A1	CND	B12	CND
A2		B11	
A3		B10	
A4	VBUS	B9	VBUS
A5	CC1	B8	SBUS
A6	D+	B7	D-
A7	D-	B6	D+
A8	SBUS	B5	CC2
A9	VBUS	B4	VBUS
A10		B3	
A11		B2	
A12	CND	B1	CND
	FINISH		APPD:

TOLERANCE

NAME(INTENDED USE)
CUSTOMER DRAWING

Guangzhou FUYOU Precision Electronic Technology Co.,Ltd.

广东富盈兴业精密科技实业有限公司

X-X ±0.30 X-X ±10° PART NO.
.XX ±0.20 .XX ±8° FY-3TC162F110-01

REACH OVER 95%.

SHALL BE FREE OF BLISTERING, GLUE MELTING AND
POOR COLOR CHANGE (DEFORMATION WITHIN TOLERANCE)

OPERATING TEMPERATURE: -40°C~+85°C

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PIN WELDING AREA GOLD FLASH.

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ADHESION TESTING. THE TIN ADHESION AREA SHOULD
REACH OVER 95%.

6. SMT REFLow Soldering (PEAK VALUE 260 °C ± 5 °C)
SHALL BE FREE OF BLISTERING, GLUE MELTING AND
POOR COLOR CHANGE (DEFORMATION WITHIN TOLERANCE)

7. OPERATING TEMPERATURE: -40°C~+85°C

TITLE: TYPE-C16P板上加长10.0L
DRAWING NO. FY-3JC162F110-01
REV. A

E

D

C

B

A

1

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